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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#20/C
Am. dt
J. McMillan
A/22/02

In re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253 ✓

Filed: December 20, 1999 ✓

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 7-10-2002 (Date)

Elizabeth Schumacher
(Printed or typed name of person signing the certificate)

Elizabeth Schumacher
(Signature of the person signing the certificate)

Sir:

PRELIMINARY AMENDMENT

Before examination, please amend the above-identified Application as follows:

IN THE CLAIMS:

(1) Please amend Claim 1 as follows:

1. (Twice amended) A wire bonding method, comprising the steps of:

C
Sub
D₁

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JUL 25 2002
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